

B3 material on bond pads of a substrate by means of different variants and embodiments, can to a very large extent be prevented.--.

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IN THE CLAIMS:

Claims 1 through 20 have been canceled.

Please replace claim 21 as follows.

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B4 21. (Amended) A method for placing a multitude of shaped parts of solder material on a bond pad arrangement of a substrate, said bond pad arrangement comprising a multitude of bond pads, and for subsequent re-melting of the shaped parts of solder material on the bond pads, method comprising the steps of:

5 arranging a template device, comprising a multitude of template apertures for accommodating shaped parts of solder material opposite a substrate comprising a bond pad arrangement, such that the shaped parts of solder material are associated with the individual bond pads;

10 applying laser energy to the shaped parts of solder material accommodated in the template apertures using a swivelling mirror and a laser device arranged at the rear of the template device such that said laser energy is applied to the shaped parts of solder material through the template device.

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Please replace claim 22 as follows.

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22. (Amended) The method according to claim 21, further comprising the steps of:  
selecting shaped parts of solder material from the bulk of shaped parts of solder material  
accommodated in the template device by filling the template apertures arranged in an aperture  
screen.

Claim 23 has not been changed by this Amendment and remains as follows:

23. The method according to claim 21, further comprising the steps of:  
filling the template apertures which are arranged in an aperture screen of the template  
device to select the shaped parts of solder material from a quantity of shaped parts of solder  
material outside the template device.

Claim 24 has not been changed by this Amendment and remains as follows:

24. The method according to one claim 21, further comprising the steps of:  
scanning of the template apertures using an optical scanning device for detecting shaped  
parts of solder material, prior to the application of laser energy to the shaped parts of solder  
material.

Claim 25 has not been changed by this Amendment and remains as follows:

25. The method according to claim 24, wherein, application of laser energy to the  
shaped parts of solder material takes place via the optical scanning device.

Claim 26 has not been changed by this Amendment and remains as follows:

26. The method according to claim 22, wherein, said step of filling of the template apertures arranged in the aperture screen of the template device takes place using a filling chamber movable over the aperture screen, said filling chamber being open towards the aperture screen.

Claim 27 has not been changed by this Amendment and remains as follows:

27. The method according to claim 22, wherein, said step of filling of the template apertures arranged in the aperture screen of the template device takes place using a paddle-wheel device guided substantially in parallel to the surface of the aperture screen, rotating on a movement axis.

Claim 28 has not been changed by this Amendment and remains as follows:

28. The method according to claim 23, wherein, said step of filling of the template apertures arranged in the aperture screen of the template device, takes place by means of pressure below atmospheric.

Claim 29 has not been changed by this Amendment and remains as follows:

29. The method according to claim 21, further comprising the steps of:  
exerting pressure on the shaped parts of solder material accommodated in the template apertures for establishing contact with the bond pads by applying pressure above atmospheric

pressure.

Please replace claim 30 as follows.

30. (Amended) A device for placing a multitude of shaped parts of solder material on a bond pad arrangement of a substrate, said bond pad arrangement comprising a multitude of bond pads, and for subsequent re-melting of the shaped parts of solder material on the bond pads, the device comprising:

5 a template device with a container for accommodating a quantity of shaped parts of solder material, said container comprising a transparent rear wall and a container wall forming an aperture screen for conveying shaped parts of solder material to the bond pad arrangement, the aperture screen comprising a selecting device such that shaped parts of solder material which have been singled out from the quantity of shaped parts of solder material and allocated  
10 to individual bond pads of the bond pad arrangement, are arranged so as to be exposed, in template apertures of the aperture screen, and thus can be exposed to laser energy from the side of the template device which is turned away from the substrate by means of a laser device.

Claim 31 has not been changed by this Amendment and remains as follows:

31. The device according to claim 30, wherein, the selecting device is movable over the aperture screen.

Claim 32 has not been changed by this Amendment and remains as follows:

32. The device according to claim 31, wherein, the selecting device is a filling chamber which can be moved over the aperture screen, said filling chamber being open towards the aperture screen.

Claim 33 has not been changed by this Amendment and remains as follows:

33. The device according to claim 31, wherein, the selecting device is a paddle-wheel device movable over the aperture screen, with radially open transport compartments delimited by paddles of the paddle-wheel device.

Claim 34 has not been changed by this Amendment and remains as follows:

34. The device according to claim 30, wherein, the selecting device is accommodated in a space closed by the template device with a rear wall opposite the aperture screen made transparent.

Claim 35 has not been changed by this Amendment and remains as follows:

35. A device for placing a multitude of shaped parts of solder material on a bond pad arrangement of a substrate, said bond pad arrangement comprising a multitude of bond pads, and for subsequent re-melting of the shaped parts of solder material on the bond pads, the device comprising;

5 a template device with a selecting device, said template device including a housing with an aperture screen comprising a multitude of template apertures for accommodating shaped

parts of solder material and a transparent rear wall, opposite the aperture screen.

Claim 36 has not been changed by this Amendment and remains as follows:

36. The device according to claim 35, wherein, the diameter of the template apertures formed in the aperture screen is smaller than the smallest diameter of the shaped parts of solder material.

Claim 37 has not been changed by this Amendment and remains as follows:

37. The device according to claim 35, wherein, the diameter of the template apertures formed in the aperture screen is larger than the largest diameter of the shaped parts of solder material, and that the distance between the aperture screen and the rear wall is smaller than the smallest diameter of the shaped parts of solder material (20).

Please replace claim 38 as follows.

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38. (Amended) The device according to claim 30, wherein, one or both of the wall structure of the aperture screen and the sidewall of the filling chamber, which can be moved over the aperture screen, is flexible across the area of the aperture screen.

Claim 39 has not been changed by this Amendment and remains as follows:

39. The device according to claim 38, wherein, the wall structure comprises at least three layers, with a flexible compression layer sandwiched between two wear-resistant surface

layers.

Claim 40 has not been changed by this Amendment and remains as follows:

40. The device according to claim 39, wherein, the compression layer is made from a plastic material, and the surface layers are made from metal.

Please add the following new claims.

138 41. (New) A device in accordance with claim 35, wherein:

said transparent rear wall has a transparent portion that exposes a plurality of said template apertures to laser radiation.

42. (New) A device in accordance with claim 30, wherein:

said transparent rear wall has a transparent portion that exposes a plurality of said template apertures to laser radiation.

43. (New) A method in accordance with claim 21, further comprising:

swivelling said swivelling mirror to direct laser energy from said laser device to a plurality of said template apertures.

#### REMARKS

The specification and claims have been amended to improve the style of this application.